

IN THE CLAIMS

1. (currently amended) A carrier for used during a dispensing process in manufacturing a semiconductor encapsulant package ~~provided with a substrate having a side surface~~having an encapsulant and a substrate having a side surface, which the carrier comprisesing:

at least one receiving part for ~~used in~~ receiving the semiconductor encapsulant package; and

a plurality of positioning pins protruding upwards from an edge of the receiving part for ~~used in~~ positioning the semiconductor encapsulant package on the carrier;

wherein an obtuse angle θ is between at least one of the positioning pins and the receiving part, and

wherein a first plane of the one of the positioning pins facing the semiconductor encapsulant package is slant~~ed~~ so that the first plane of the one of the positioning pins is only abutted against a lower edge of the side surface of the substrate and a gap is between the one of the positioning pins and the seimiconductor encapsulant package.

2. (original) The carrier as claimed in Claim 1, wherein the semiconductor encapsulant package exerts a friction force and a gliding force when contacting with the positioning pins, and the obtuse angle θ between the positioning pin and the receiving part allows the friction force larger than the gliding force.

3. (original) The carrier as claimed in Claim 1, wherein the obtuse angle θ between the positioning pin and receiving part is larger than 91° .

4. (previously presented) The carrier as claimed in Claim 1, wherein the obtuse angle θ between the positioning pin and the receiving part is from 91° to 110° .

5. (previously presented) The carrier as claimed in Claim 1, wherein the obtuse angle θ between the positioning pin and the receiving part is from 91° to 96° .

6. (previously presented) The carrier as claimed in Claim 1, wherein a second plane of the positioning pin opposite the semiconductor encapsulant package is vertical, and the second plane of the positioning pin is at an angle of about 90° to the receiving part.

7. (currently amended) The carrier as claimed in Claim 1, wherein a ~~first plane of the positioning pins facing the semiconductor encapsulant package is slant and~~ a second plane of the positioning pin opposite the semiconductor encapsulant package is also slanted and; ~~wherein the second plane is~~ substantially parallel to the first plane.

8. (original) The carrier as claimed in Claim 1, wherein the positioning pins and the receiving parts are integrally formed.

9. (previously presented) The carrier as claimed in Claim 2, wherein the obtuse angle θ between the positioning pin and the receiving part is from 91° to 110° .

10. (previously presented) The carrier as claimed in Claim 3, wherein the obtuse angle θ between the positioning pin and the receiving part is from 91° to 110°

11. (previously presented) The carrier as claimed in Claim 2, wherein the obtuse angle θ between the positioning pin and the receiving part is from 91° to 96° .

.12. (previously presented) The carrier as claimed in Claim 3, wherein the obtuse angle θ between the positioning pin and the receiving part is from 91° to 96° .